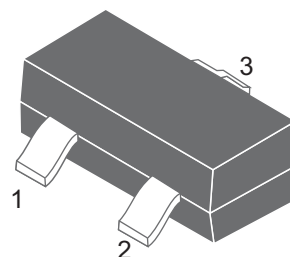
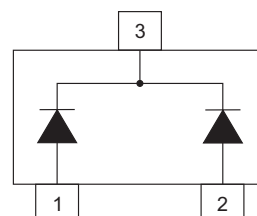


Features

- We declare that the material of product compliance with RoHS requirements and Halogen Free
- Extremely Fast Switching Speed
- Low Forward Voltage — 0.35 Volts (Typ) @ $I_F = 10$ mAdc



SOT-23



Maximum & Thermal Characteristics Ratings ($T_A=25^\circ\text{C}$ unless otherwise noted)

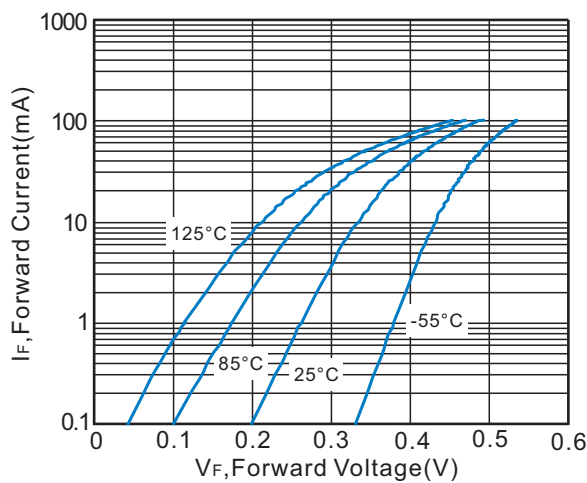
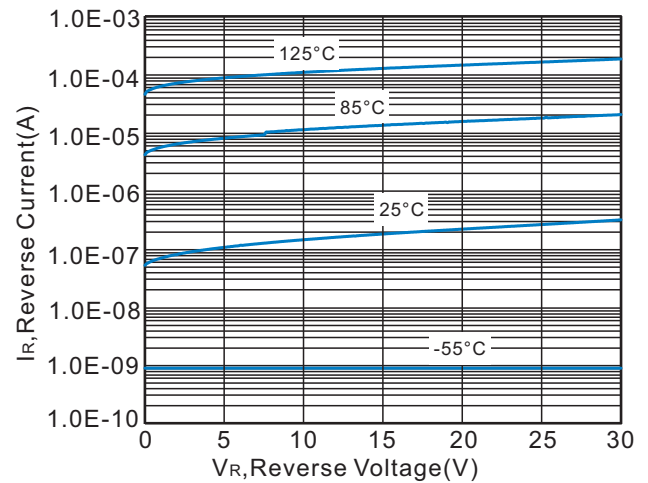
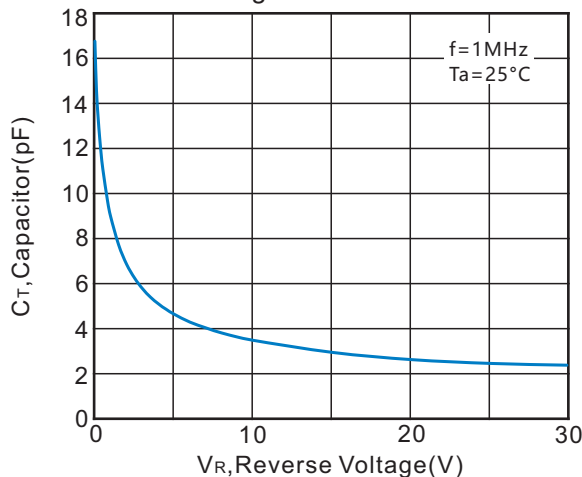
Parameter	Symbol	Value	Units
DC Reverse Voltage	V_R	30	V
Forward Current	I_F	200	mAdc
Total Device Dissipation, FR-5 Board ⁽¹⁾ @ $T_A = 25^\circ\text{C}$ Derate above 25°C	P_D	225 1.8	mW mW/ $^\circ\text{C}$
Thermal Resistance, Junction-to-Ambient ⁽¹⁾	$R_{\theta JA}$	556	$^\circ\text{C/W}$
Junction and Storage temperature	T_J, T_{STG}	-55~+125	$^\circ\text{C}$

Note : 1. FR-5 = 1.0×0.75×0.062 in.

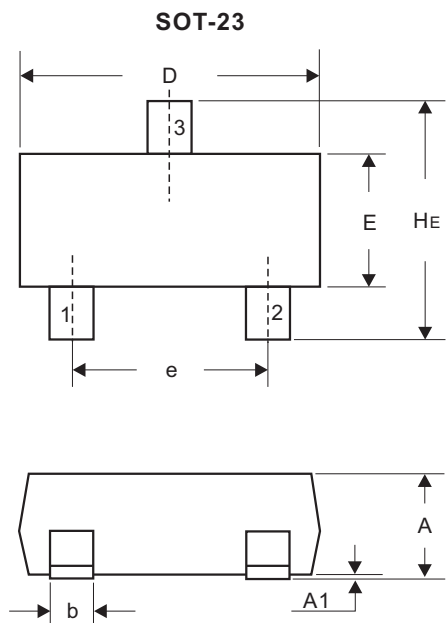
Electrical Characteristics($T_A=25^{\circ}\text{C}$ unless otherwise specified)

Parameter	Symbol	Min.	Typ.	Max.	Units
Reverse Breakdown Voltage($I_R = 10\mu\text{Adc}$)	V_{BR}	30			V
Reverse Voltage Leakage Current($V_R = 25\text{Vdc}$)	I_R		0.5	2	μA
Diode Capacitance($V_R = 1.0\text{V}$, $f = 1.0\text{ MHz}$)	C_T			10	pF
Forward Voltage ($I_F = 0.1\text{ mAdc}$) ($I_F = 1\text{ mAdc}$) ($I_F = 10\text{ mAdc}$) ($I_F = 30\text{ mAdc}$) ($I_F = 100\text{ mAdc}$)	V_F		0.22 0.29 0.35 0.41 0.52	0.24 0.32 0.4 0.5 1	V
Reverse Recovery Time ($I_F = I_R = 10\text{ mAdc}$, $I_{R(REC)} = 1.0\text{ mAdc}$)	t_{rr}			5	ns
Repetitive Peak Forward Current	I_{FRM}			300	mA
Non-Repetitive Peak Forward Current($t < 1.0\text{ s}$)	I_{FSM}			600	mA

Characteristic Curves ($T_A=25^{\circ}\text{C}$ unless otherwise noted)

 Fig.1 I_F vs. V_F

 Fig.2 I_R vs. V_R

 Fig.3 C_T vs. V_R


Dimensions(SOT-23)



DIM	Millimeters		Inches	
	Min	Max	Min	Max
A	0.89	1.11	0.035	0.044
A1	0.01	0.10	0.001	0.004
b	0.37	0.50	0.015	0.020
c	0.09	0.18	0.003	0.007
D	2.80	3.04	0.110	0.120
E	1.20	1.40	0.047	0.055
e	1.78	2.04	0.070	0.081
L	0.35	0.69	0.014	0.029
H _E	2.10	2.64	0.083	0.104

Recommended Mounting Pad Layout

